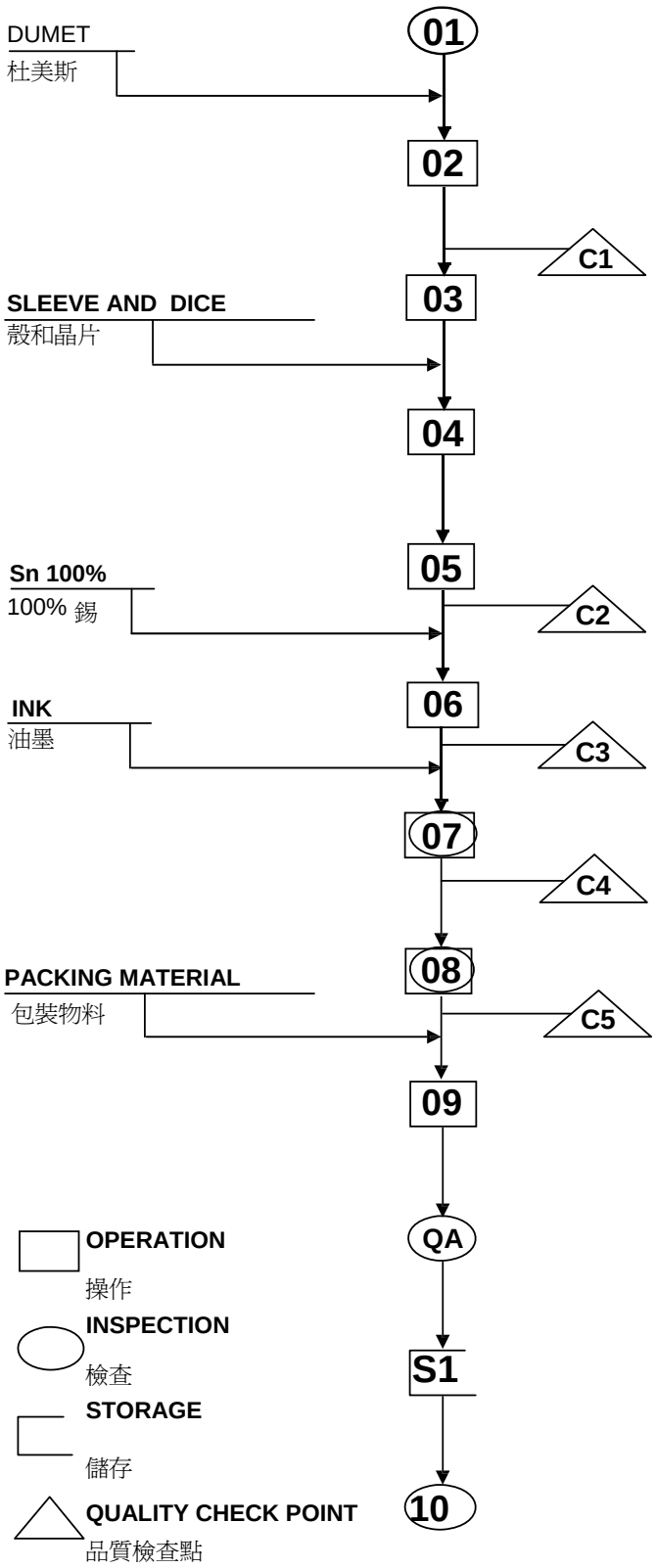
CHINA BASE INTERNATIONAL

PROCESS FLOW CHART FOR SMD GLASS DIODE

二極管工序流程圖

www.china-base.com.hk



01=MATERIAL INCOMING INSPECTION
來料檢查

02=PRODUCTION OF TERMINAL
銅釘生產

03=CLEANING OF TERMINAL
銅釘清洗 **GLASS**

04=ASSEMBLING 玻
裝配

05=GLASS SEALING
玻封

06=PLATING
上錫

07=100% TESTING AND MARKING
100%測試，嗖圈

08=SECOND TIME 100% TESTING AND TAPING
二次100%測試，上帶

09=PACKING
包裝

10=FINAL INSPECTION BEFORE DISPATCHING
出廠驗收檢查

QA=QUALITY ASSURANCE
最終檢查

S1=STORAGE
倉儲

C1=QUALITY CONTROL AND MONITORING OF LEAD WIRE
引線IPQC過程檢查及控制

C2=QUALITY CONTROL AND MONITORING OF GLASS SEALING
玻封品質控制

C3=QUALITY CONTROL AND MONITORING OF PLATING
上錫品質檢查

C4=QUALITY CONTROL AND MONITORING OF MARKING
嗖圈品質檢查及控制

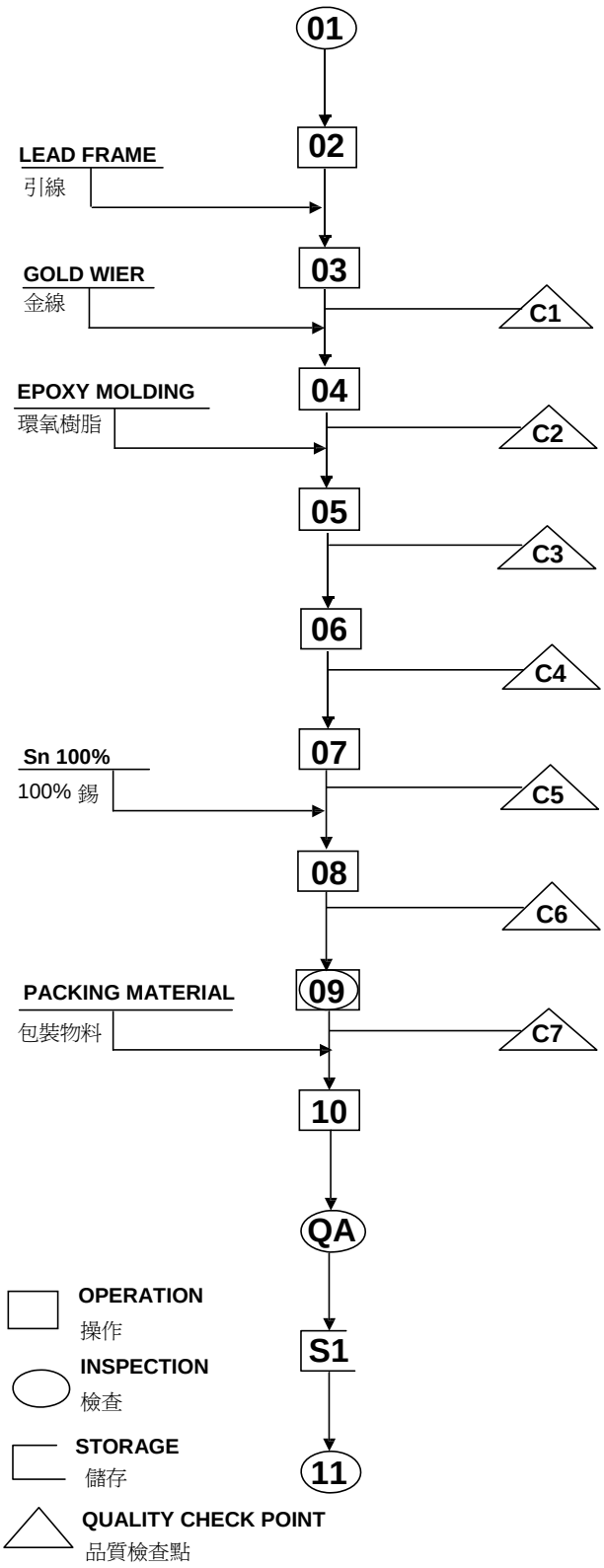
C5=QUALITY CONTROL AND MONITORING OF TAPING
上帶品質檢查及控制

Copyright © All right reserved: Heyuan China Base Electronics Technology Co., Ltd.

PROCESS FLOW CHART FOR SOD DIODE

SOD 二極管工序流程圖

www.china-base.com.hk



01=MATERIAL INCOMING INSPECTION
來料檢查

02=WAFER SAWING
晶片切割

03=DIE BONDING
晶片焊接

04=WIRE BONDING
焊線焊接

05=MOLDING, TRIMMING
注塑, 冲切水口

06=PLATING
上錫

07=LASER MARKING
激光刻字

08=CUTTING, FORMING
剪脚, 成型

09=100% TESTING & TAPING
100%測試，上帶

10=PACKING
包裝

11=FINAL INSPECTION BEFORE DISPATCHING
出廠驗收檢測

QA=QUALITY ASSURANCE
最終檢查

S1=STORAGE
倉儲

C1=QUALITY CONTROL AND MONITORING OF DIE BONDING
晶片焊接過程檢查及控制

C2=QUALITY CONTROL AND MONITORING OF WIRE BONDING
焊線IPQC過程檢查控制

C3=QUALITY CONTROL AND MONITORING OF MOLDING
注塑IPQC過程檢查及控制

C4=QUALITY CONTROL AND MONITORING OF PLATING
上錫IPQC過程檢查及控制

C5=QUALITY CONTROL AND MONITORING OF LASER MARKING
刻字過程檢查控制

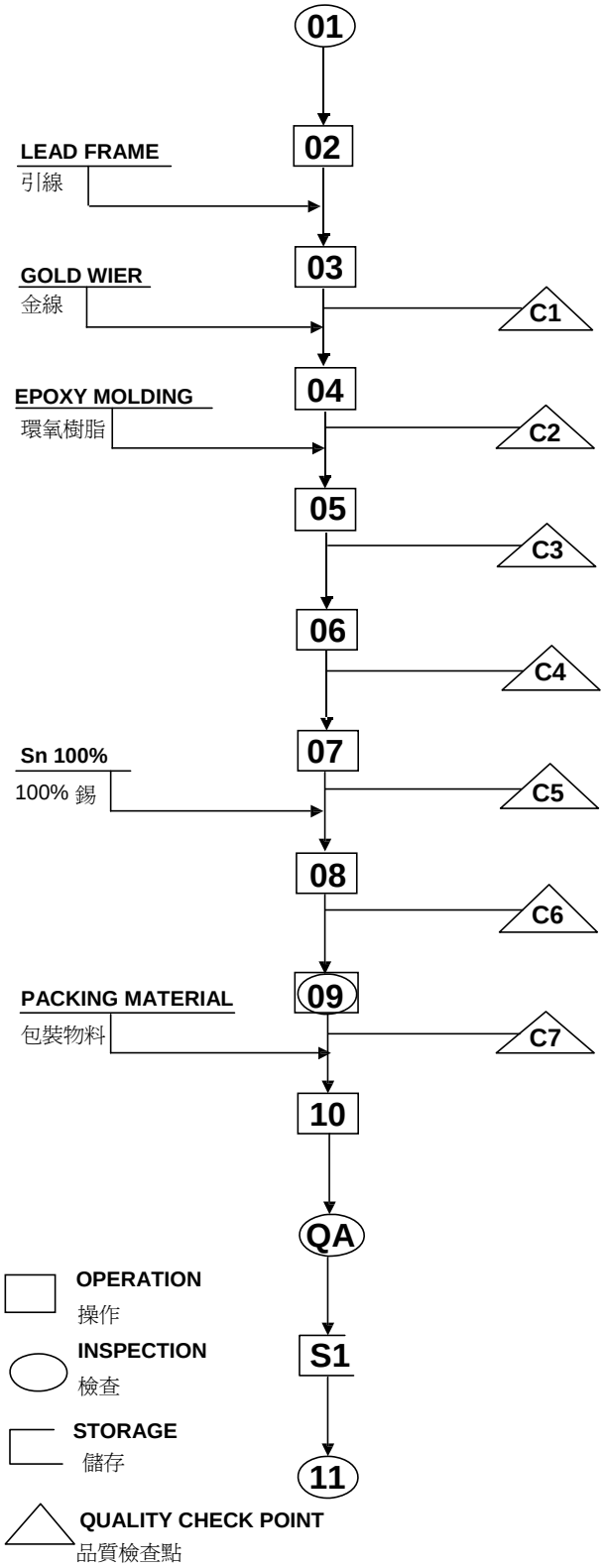
C6=QUALITY CONTROL AND MONITORING OF FORMING
成型過程檢查及控制

C7=QUALITY CONTROL AND MONITORING OF TESTING & TAPING
測試上帶IPQC過程檢查及控制

Copyright © All right reserved: Heyuan China Base Electronics Technology Co., Ltd.

PROCESS FLOW CHART FOR SOT-23 DIODE

SOT-23 二極管工序流程圖



01=MATERIAL INCOMING INSPECTION
來料檢查

02=WAFER SAWING
晶片切割

03=DIE BONDING
晶片焊接

04=WIRE BONDING
焊線焊接

05=MOLDING, TRIMMING
注塑, 冲切水口

06=PLATING
上錫

07=LASER MARKING
激光刻字

08=CUTTING, FORMING
剪脚, 成型

09= 100% TESTING & TAPING
100%測試，上帶

10=PACKING
包裝

11=FINAL INSPECTION BEFORE DISPATCHING
出廠驗收檢測

QA=QUALITY ASSURANCE
最終檢查

S1=STORAGE
倉儲

C1=QUALITY CONTROL AND MONITORING OF DIE BONDING
晶片焊接過程檢查及控制

C2=QUALITY CONTROL AND MONITORING OF WIRE BONDING
焊線IPQC過程檢查及控制

C3=QUALITY CONTROL AND MONITORING OF MOLDING
注塑IPQC過程檢查及控制

C4=QUALITY CONTROL AND MONITORING OF PLATING
上錫IPQC過程檢查及控制

C5=QUALITY CONTROL AND MONITORING OF LASER MARKING
激光刻字檢查及控制

C6=QUALITY CONTROL AND MONITORING OF FORMING
成型過程檢查及控制

C7=QUALITY CONTROL AND MONITORING OF TESTING & TAPING
測試上帶IPQC過程檢查及控制

Copyright © All right reserved: Heyuan China Base Electronics Technology Co., Ltd.